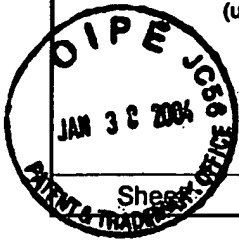


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INFORMATION DISCLOSURE CITATION (use as many sheets as necessary)				Application Number	10/660,926
				Filing Date	September 12, 2003
				First Named Inventor	Wen J. Meng
				Art Unit	3725
				Examiner Name	D. Suhol
Sheet <u>1</u> of <u>1</u>				Attorney Docket Number	Meng 0310



U.S. PATENT DOCUMENTS					
Exam. Initial	Document No.	Date	Name	Class	Subcl.

FOREIGN PATENT DOCUMENTS				
Exam. Initial	Foreign Patent Document Country Code / Number / Kind	Publication Date MM-DD-YY	Name of Patentee or Applicant of Cited Document	Translation ?

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)	
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EXAMINER SIGNATURE /Dmitry Suhol/ (05/11/2006)	DATE CONSIDERED 05/11/2006
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